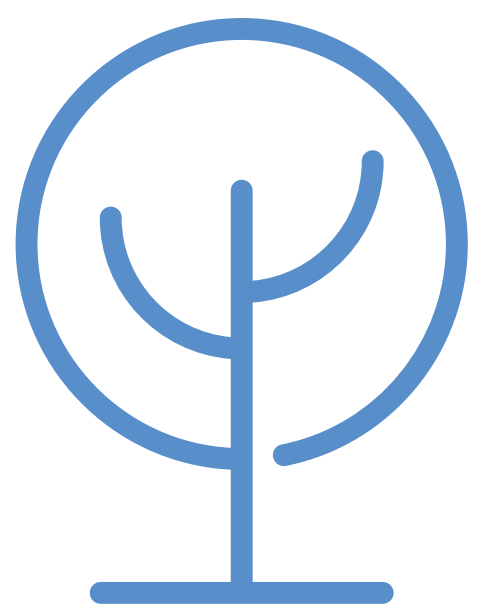


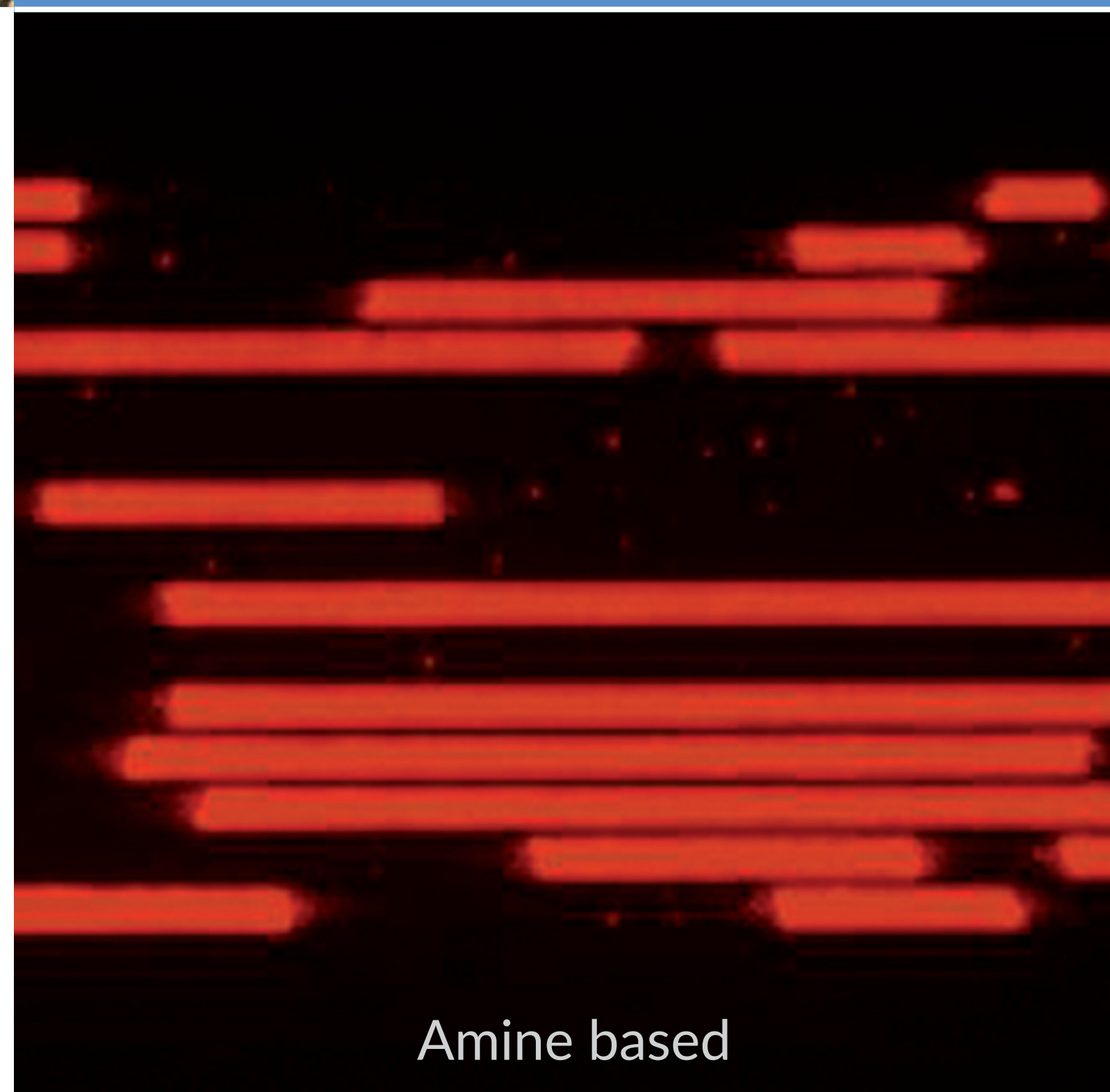
Photoresist stripping
of ultra fine lines common to
package substrates

UV image showing residues after stripping (10/10 µm L&S; red indicates photoresist residues) – completely stripped after ResistStrip® IC-Series

ResistStrip® IC-conditions
50 – 65 °C / 80 – 120 s



Significant reduction in waste
volumes over amine systems



Amine based



ResistStrip® IC-Series

Fast and complete stripping of photoresists

ResistStrip® IC is specially formulated to meet the demands of ultra fine line dry film stripping within the manufacturing of package substrates. The single process step suites all types of stripping equipment with either „dashpot“ or bulk storage style replenishment systems. ResistStrip® IC reduces waste volumes over amine systems significantly. The even and rapid strip rate enables highest throughput.

Features and benefits

- Minimal swelling of resists to ensure maximum stripping without entrapment
- Minimal attack on copper surfaces due to the use of an integrated inhibitor package
- Two highly concentrated stripper solutions for easier handling
- Suitable for use with most alkali-soluble photoresists
- For use in conveyORIZED spray equipment